



## Description

The AO4718 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## General Features

$V_{DS} = 30V$   $I_D = 15A$

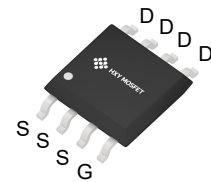
$R_{DS(ON)} < 10m\Omega$  @  $V_{GS}=10V$

## Application

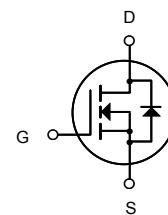
Battery protection

Load switch

Uninterruptible power supply



SOP-8  
(SO-8)



N-Channel MOSFET

## Ordering Information

| Product ID | Pack        | Brand      | Qty(PCS) |
|------------|-------------|------------|----------|
| AO4718     | SOP-8(SO-8) | HXY MOSFET | 3000     |

## Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| Symbol               | Parameter                                                | Rating     | Units |
|----------------------|----------------------------------------------------------|------------|-------|
| $V_{DS}$             | Drain-Source Voltage                                     | 30         | V     |
| $V_{GS}$             | Gate-Source Voltage                                      | $\pm 20$   | V     |
| $I_D@T_A=25^\circ C$ | Continuous Drain Current <sup>1</sup>                    | 15         | A     |
| $I_D@T_A=70^\circ C$ | Continuous Drain Current <sup>1</sup>                    | 8          | A     |
| $I_{DM}$             | Pulsed Drain Current <sup>2</sup>                        | 45         | A     |
| EAS                  | Single Pulse Avalanche Energy <sup>3</sup>               | 12         | mJ    |
| $P_D@T_A=25^\circ C$ | Total Power Dissipation <sup>4</sup>                     | 15         | W     |
| $T_{STG}$            | Storage Temperature Range                                | -55 to 150 | °C    |
| $T_J$                | Operating Junction Temperature Range                     | -55 to 150 | °C    |
| $R_{\theta JA}$      | Thermal Resistance Junction-ambient <sup>1</sup> (t≤10s) | 85         | °C/W  |
|                      | Thermal Resistance Junction-ambient <sup>1</sup>         | 25         | °C/W  |



**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

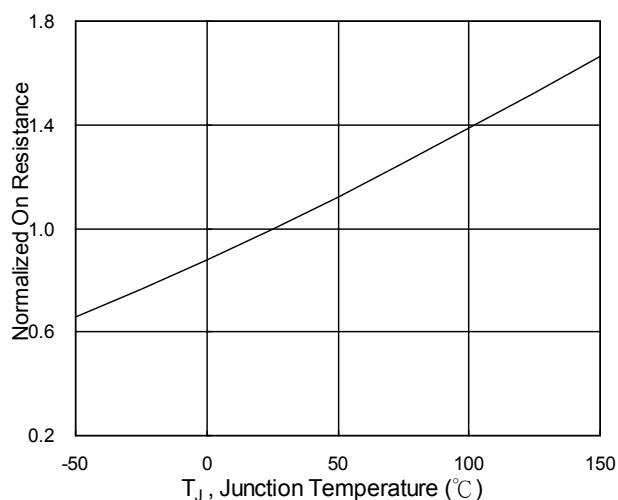
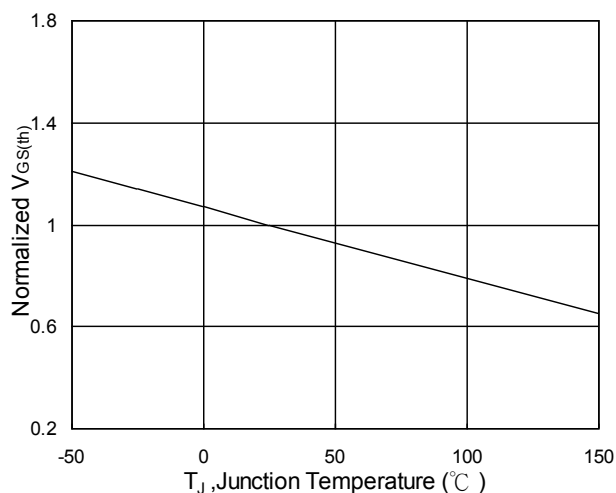
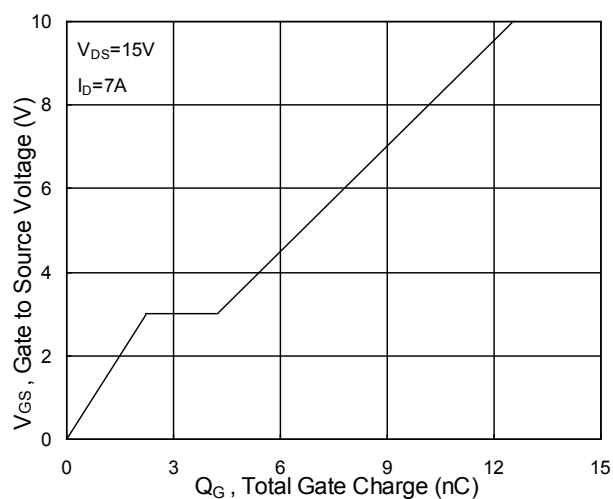
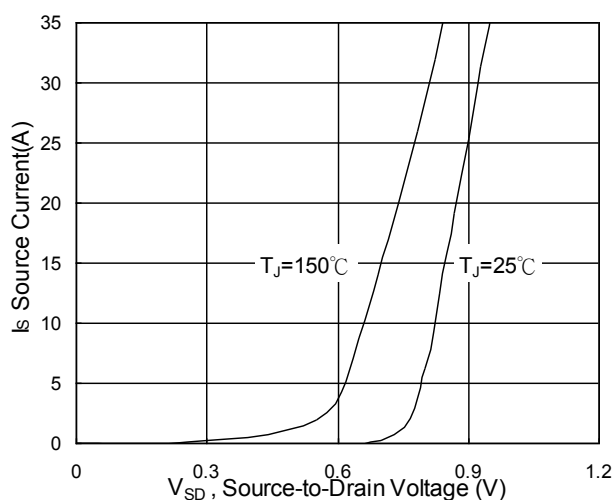
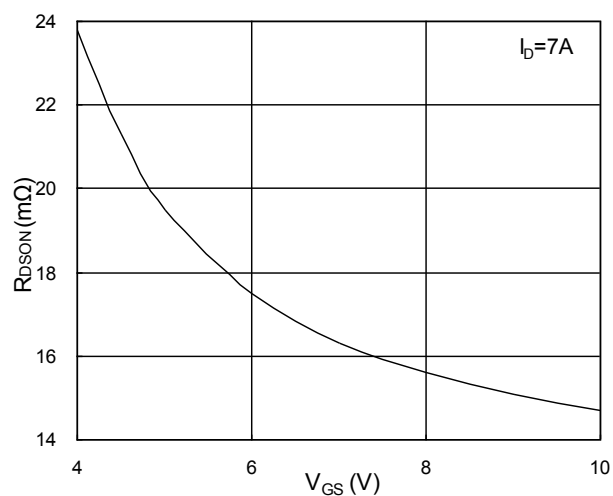
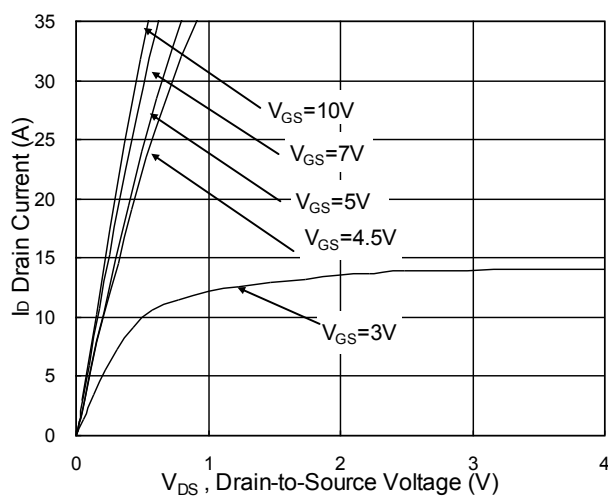
| Symbol                       | Parameter                                      | Conditions                                                | Min. | Typ.  | Max.      | Unit                  |
|------------------------------|------------------------------------------------|-----------------------------------------------------------|------|-------|-----------|-----------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                              | 30   | ---   | ---       | V                     |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$      | ---  | 0.034 | ---       | $V/^{\circ}\text{C}$  |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=7A$                                   | ---  | 8     | 10        | $m\Omega$             |
|                              |                                                | $V_{GS}=4.5V$ , $I_D=4A$                                  | ---  | 12    | 15        |                       |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                          | 1.2  | 1.4   | 2.5       | V                     |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |                                                           | ---  | -3.84 | ---       | $mV/^{\circ}\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=25^{\circ}\text{C}$     | ---  | ---   | 1         | $\mu A$               |
|                              |                                                | $V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=55^{\circ}\text{C}$     | ---  | ---   | 5         |                       |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                            | ---  | ---   | $\pm 100$ | nA                    |
| $g_{fs}$                     | Forward Transconductance                       | $V_{DS}=5V$ , $I_D=7A$                                    | ---  | 6.2   | ---       | S                     |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1\text{MHz}$               | ---  | 1.04  | 2.1       | $\Omega$              |
| $Q_g$                        | Total Gate Charge (4.5V)                       | $V_{DS}=15V$ , $V_{GS}=4.5V$ , $I_D=7A$                   | ---  | 6     | 8.4       | nC                    |
| $Q_{gs}$                     | Gate-Source Charge                             |                                                           | ---  | 2.2   | 3.1       |                       |
| $Q_{gd}$                     | Gate-Drain Charge                              |                                                           | ---  | 2     | 2.8       |                       |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=15V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$<br>$I_D=7A$ | ---  | 1.2   | 2.4       | ns                    |
| $T_r$                        | Rise Time                                      |                                                           | ---  | 40    | 72.0      |                       |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |                                                           | ---  | 18    | 36.0      |                       |
| $T_f$                        | Fall Time                                      |                                                           | ---  | 7.2   | 14.4      |                       |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V$ , $V_{GS}=0V$ , $f=1\text{MHz}$              | ---  | 983   | 1616      | pF                    |
| $C_{oss}$                    | Output Capacitance                             |                                                           | ---  | 147   | 207.8     |                       |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |                                                           | ---  | 109   | 162.6     |                       |
| $I_S$                        | Continuous Source Current <sup>1,5</sup>       | $V_G=V_D=0V$ , Force Current                              | ---  | ---   | 15        | A                     |
| $I_{SM}$                     | Pulsed Source Current <sup>2,5</sup>           |                                                           | ---  | ---   | 35        | A                     |
| $V_{SD}$                     | Diode Forward Voltage <sup>2</sup>             | $V_{GS}=0V$ , $I_S=1A$ , $T_J=25^{\circ}\text{C}$         | ---  | ---   | 1.2       | V                     |
| $t_{rr}$                     | Reverse Recovery Time                          | $I_F=7A$ , $dI/dt=100A/\mu s$ , $T_J=25^{\circ}\text{C}$  | ---  | 7.2   | ---       | nS                    |
| $Q_{rr}$                     | Reverse Recovery Charge                        |                                                           | ---  | 2.9   | ---       | nC                    |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=20A$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.



## Typical Characteristics



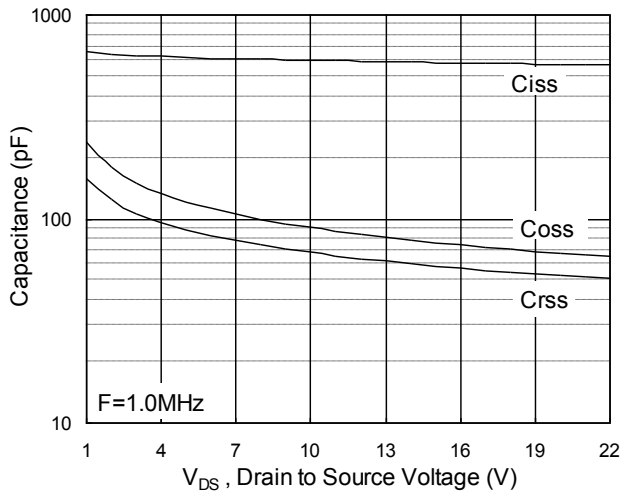


Fig.7 Capacitance

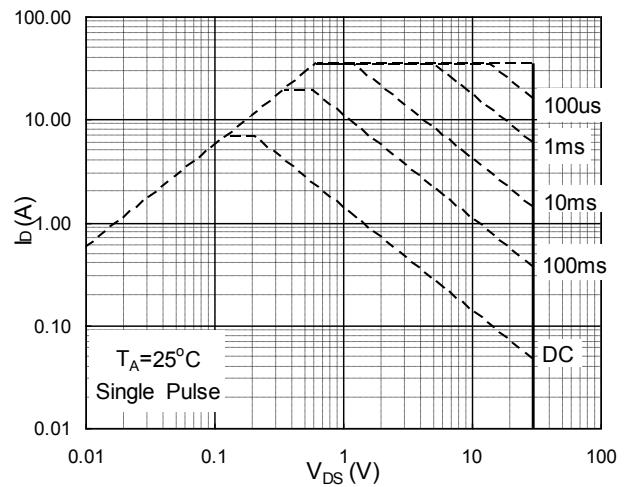


Fig.8 Safe Operating Area

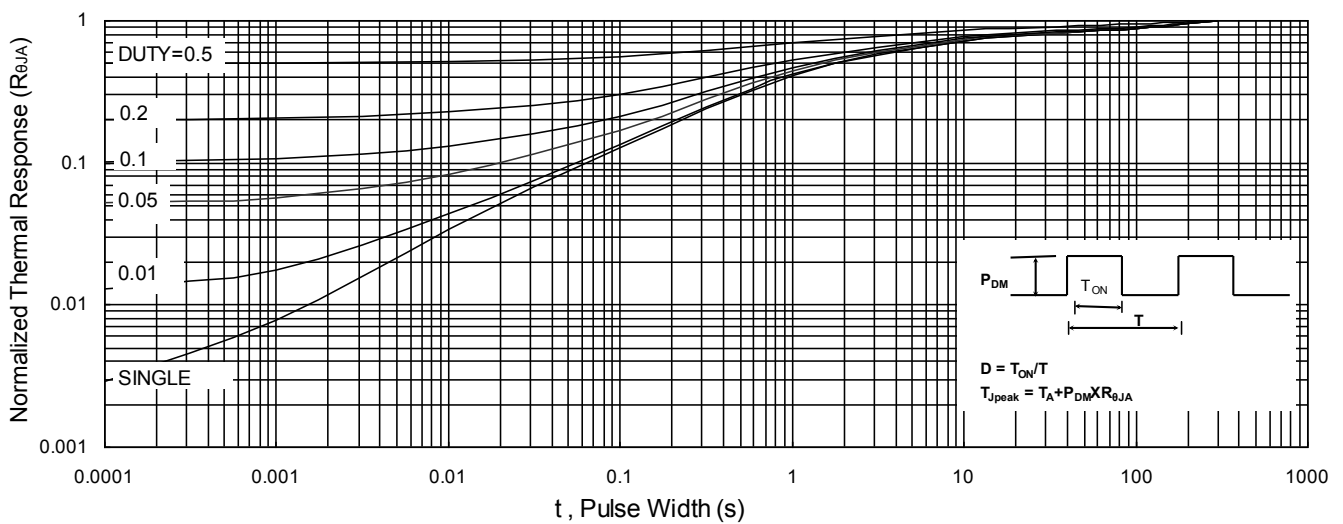


Fig.9 Normalized Maximum Transient Thermal Impedance

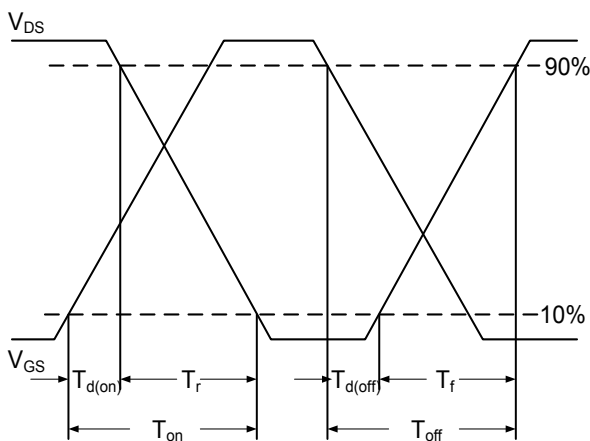


Fig.10 Switching Time Waveform

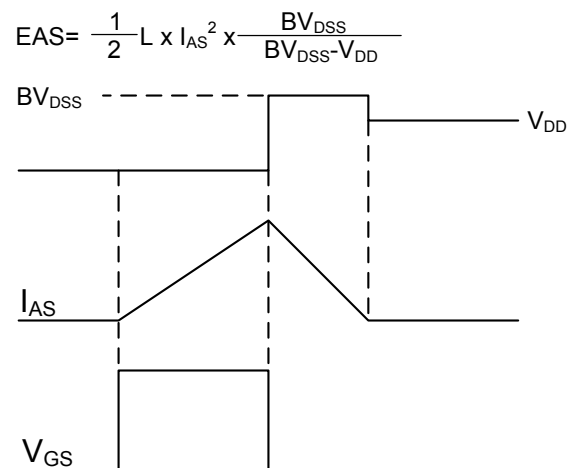
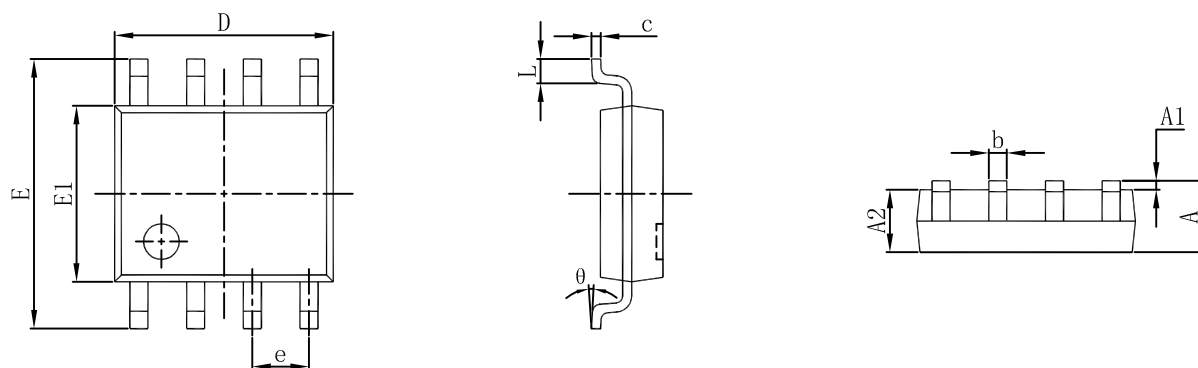


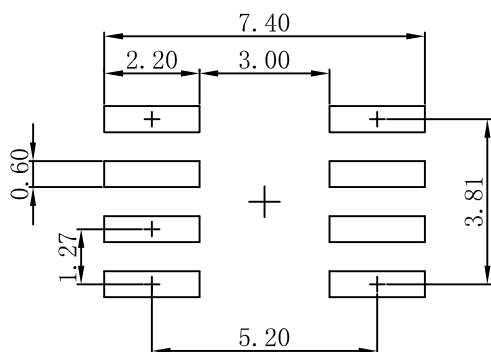
Fig.11 Unclamped Inductive Switching Waveform



## SOP-8(SO-8) Package Outline Dimensions



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.007                | 0.010 |
| D      | 4.800                     | 5.000 | 0.189                | 0.197 |
| e      | 1.270 (BSC)               |       | 0.050 (BSC)          |       |
| E      | 5.800                     | 6.200 | 0.228                | 0.244 |
| E1     | 3.800                     | 4.000 | 0.150                | 0.157 |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |



Note:  
1. Controlling dimension; in millimeters.  
2. General tolerance:  $\pm 0.05\text{mm}$ .  
3. The pad layout is for reference purposes only.



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